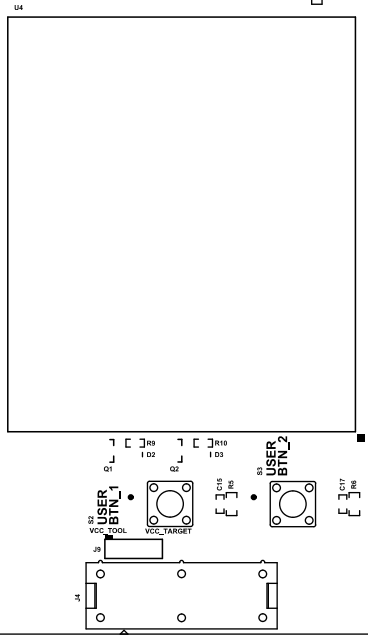
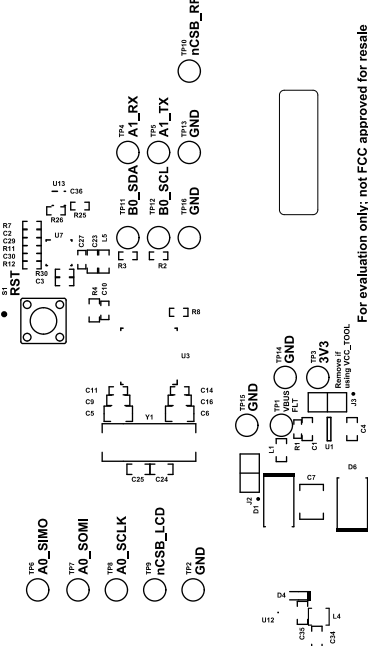
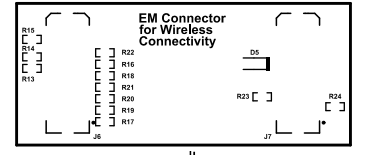
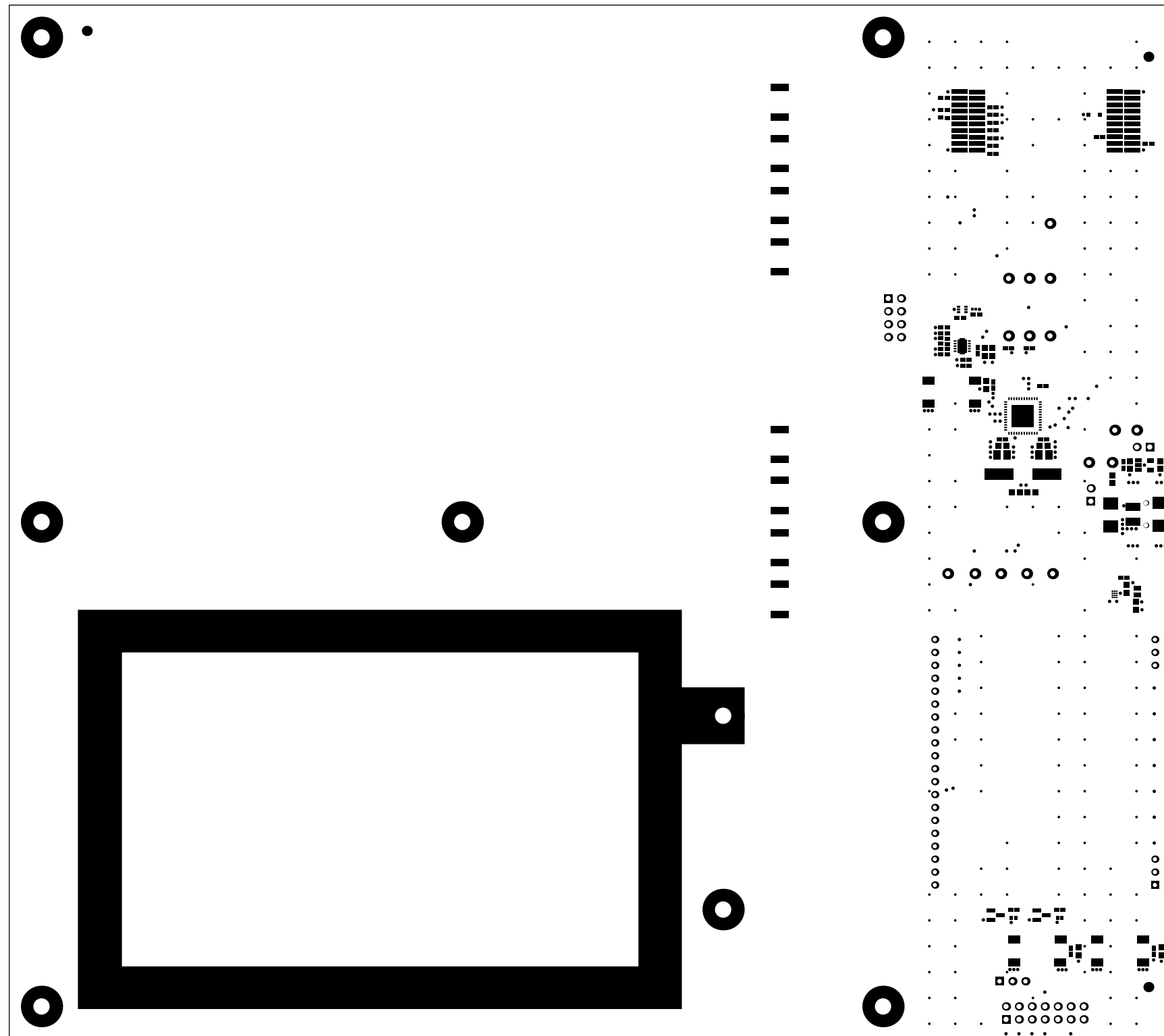


**TEXAS INSTRUMENTS**  
 ISE4010 / TIDA-00220  
 Rev. E2

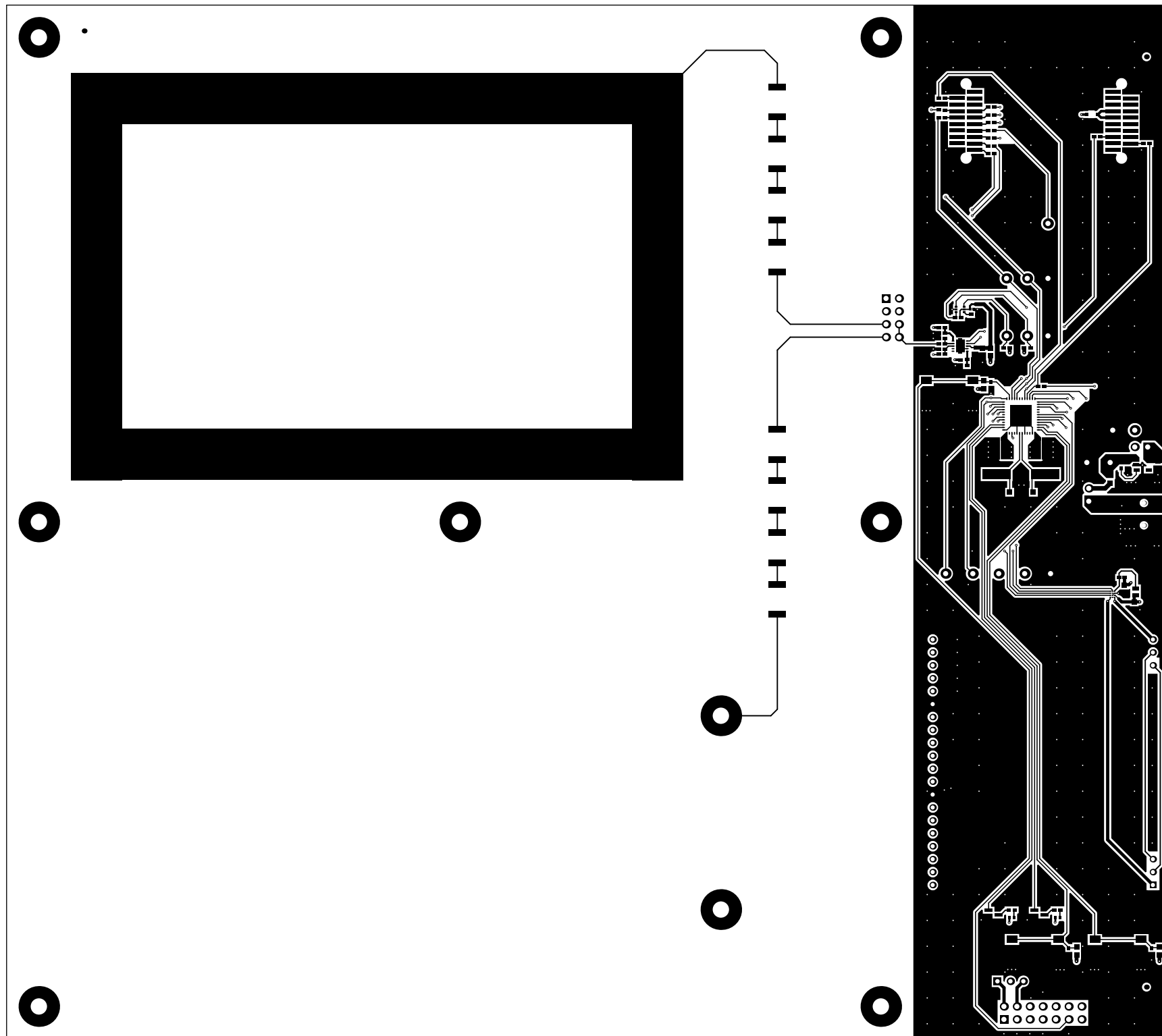


For evaluation only, not FCC approved for resale

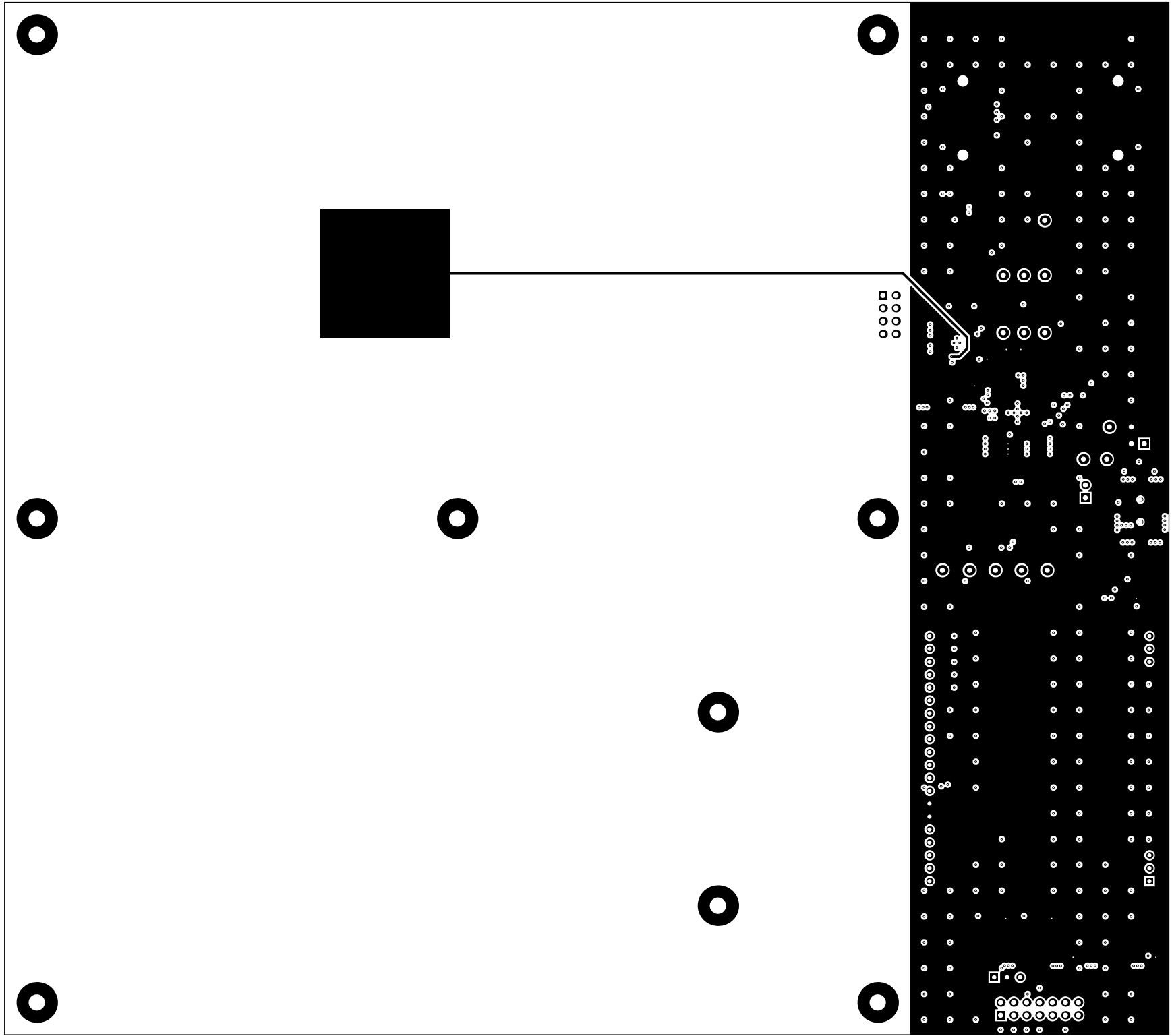
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/14/2014 2:57:34 PM	TEXAS INSTRUMENTS	



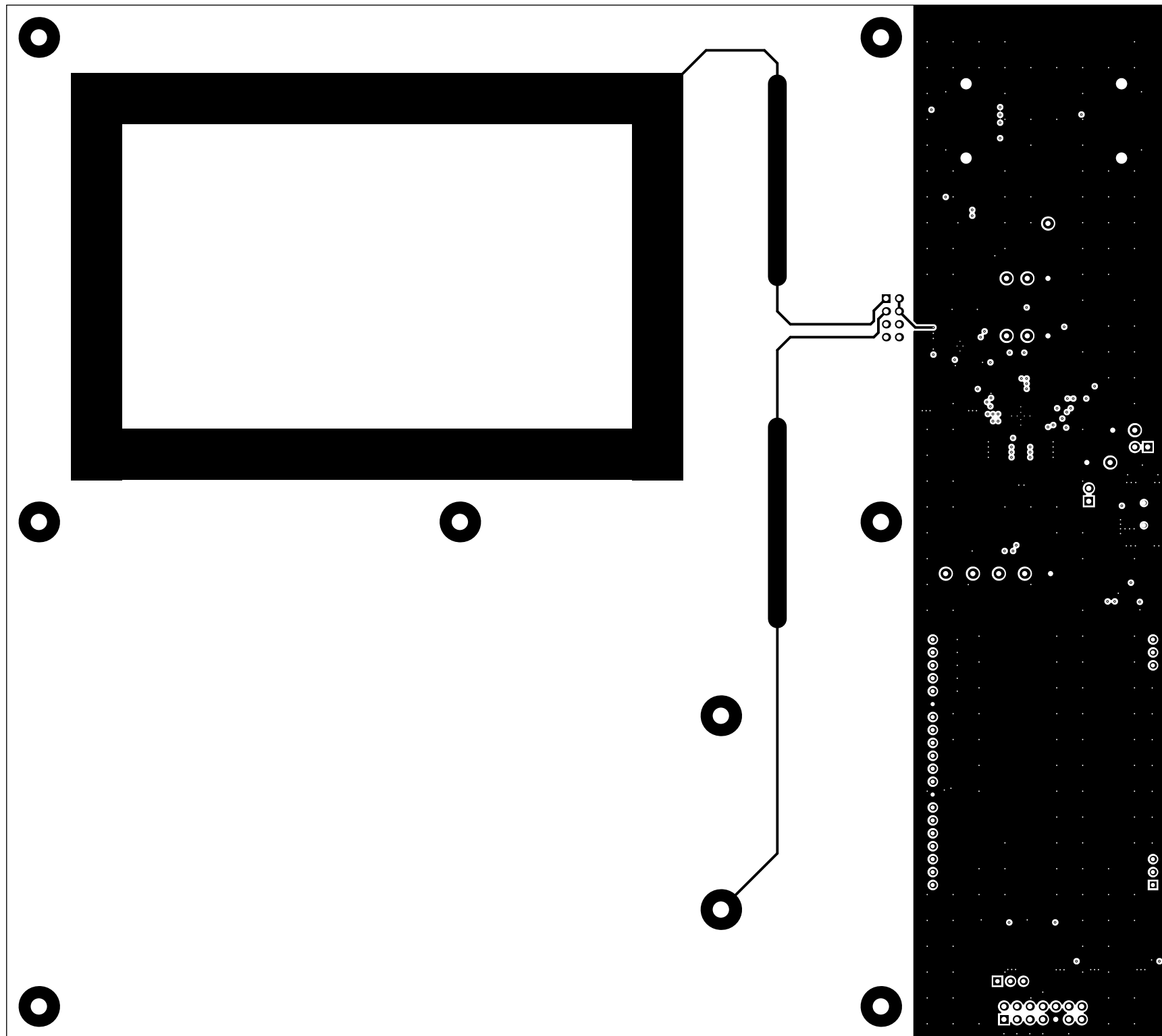
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/14/2014 2:57:35 PM	TEXAS INSTRUMENTS	



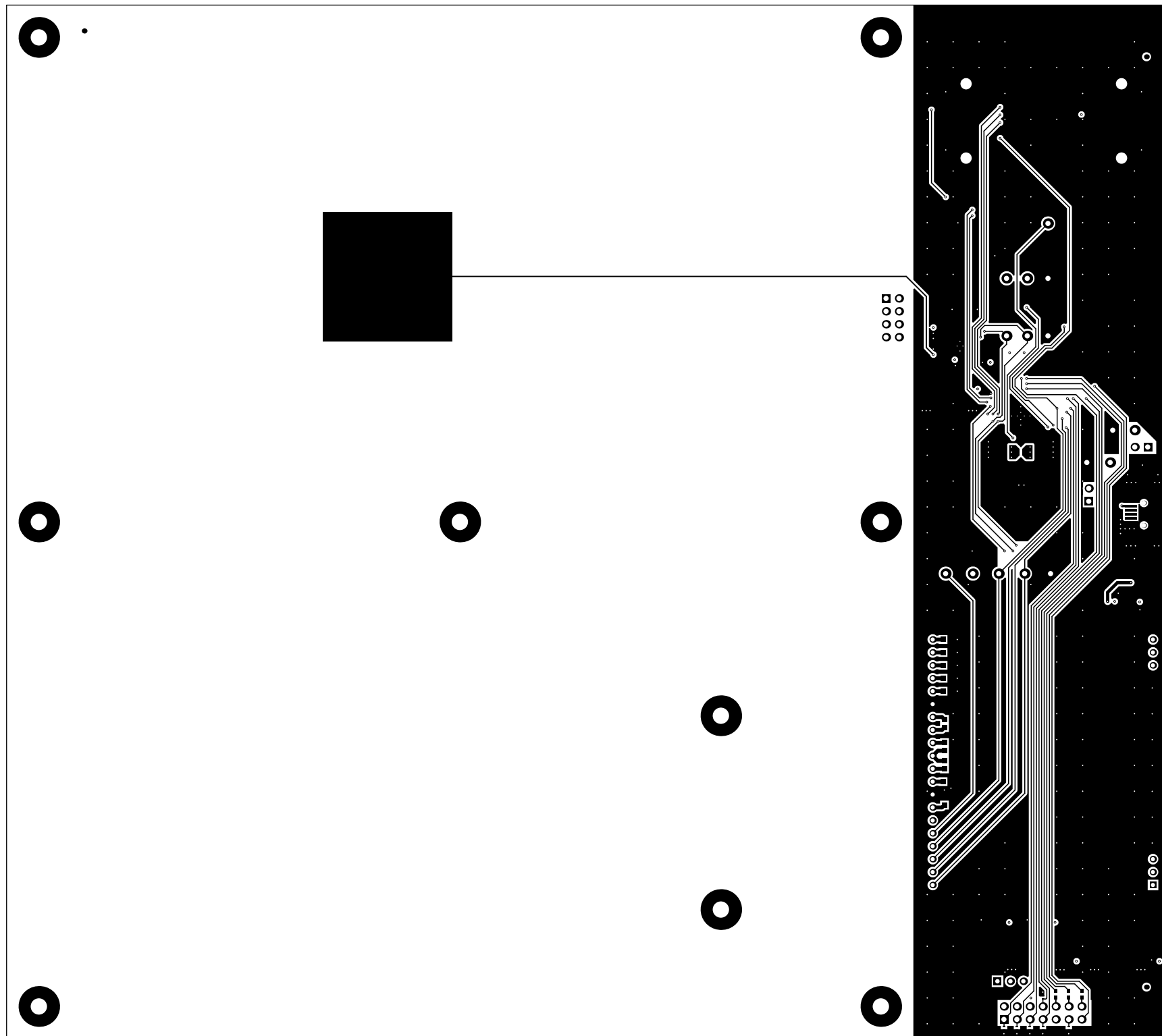
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/14/2014 2:57:35 PM	TEXAS INSTRUMENTS	



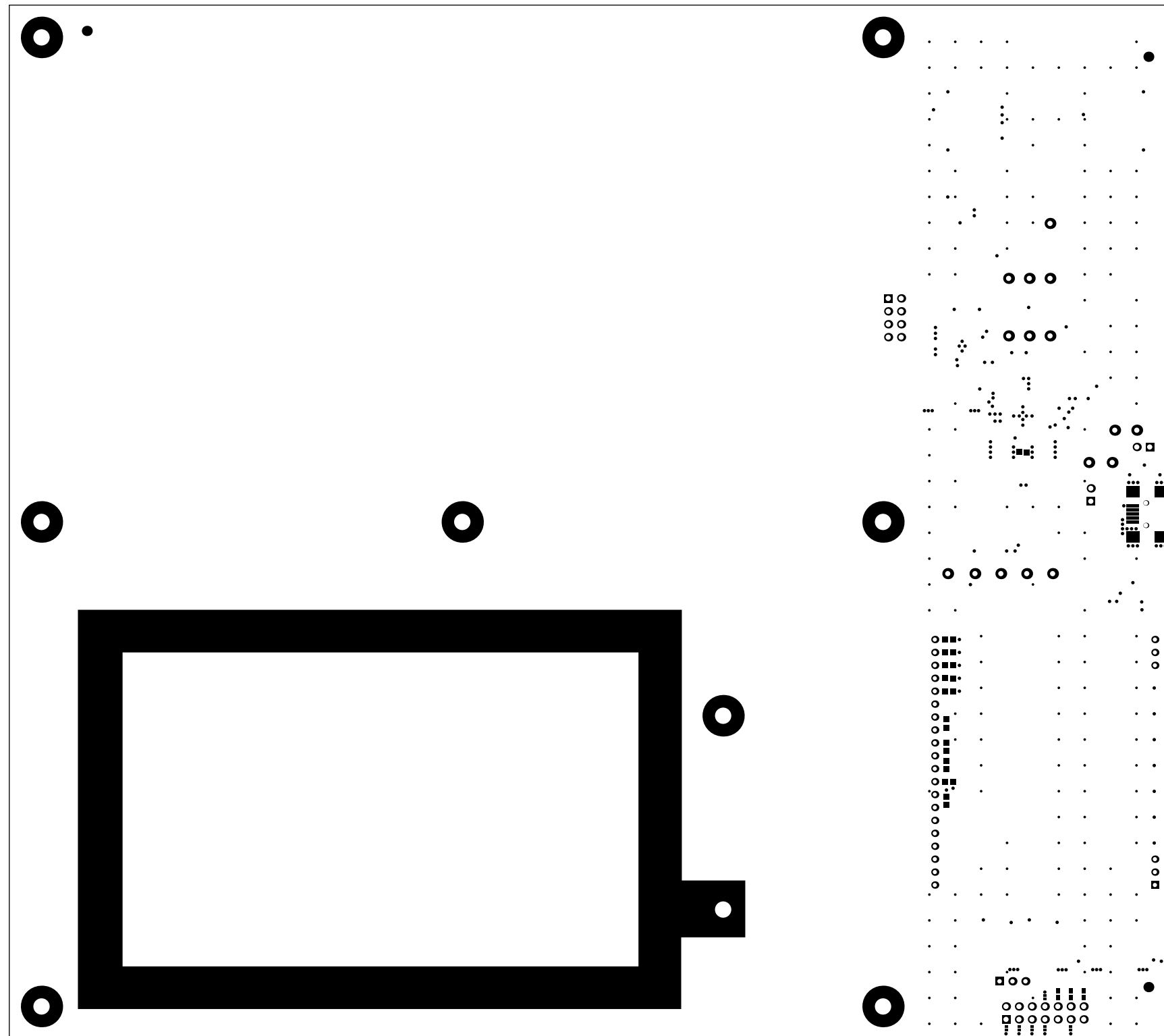
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - PWR			
PLOT NAME = MidLayer1	GENERATED : 10/14/2014 2:57:36 PM	TEXAS INSTRUMENTS	



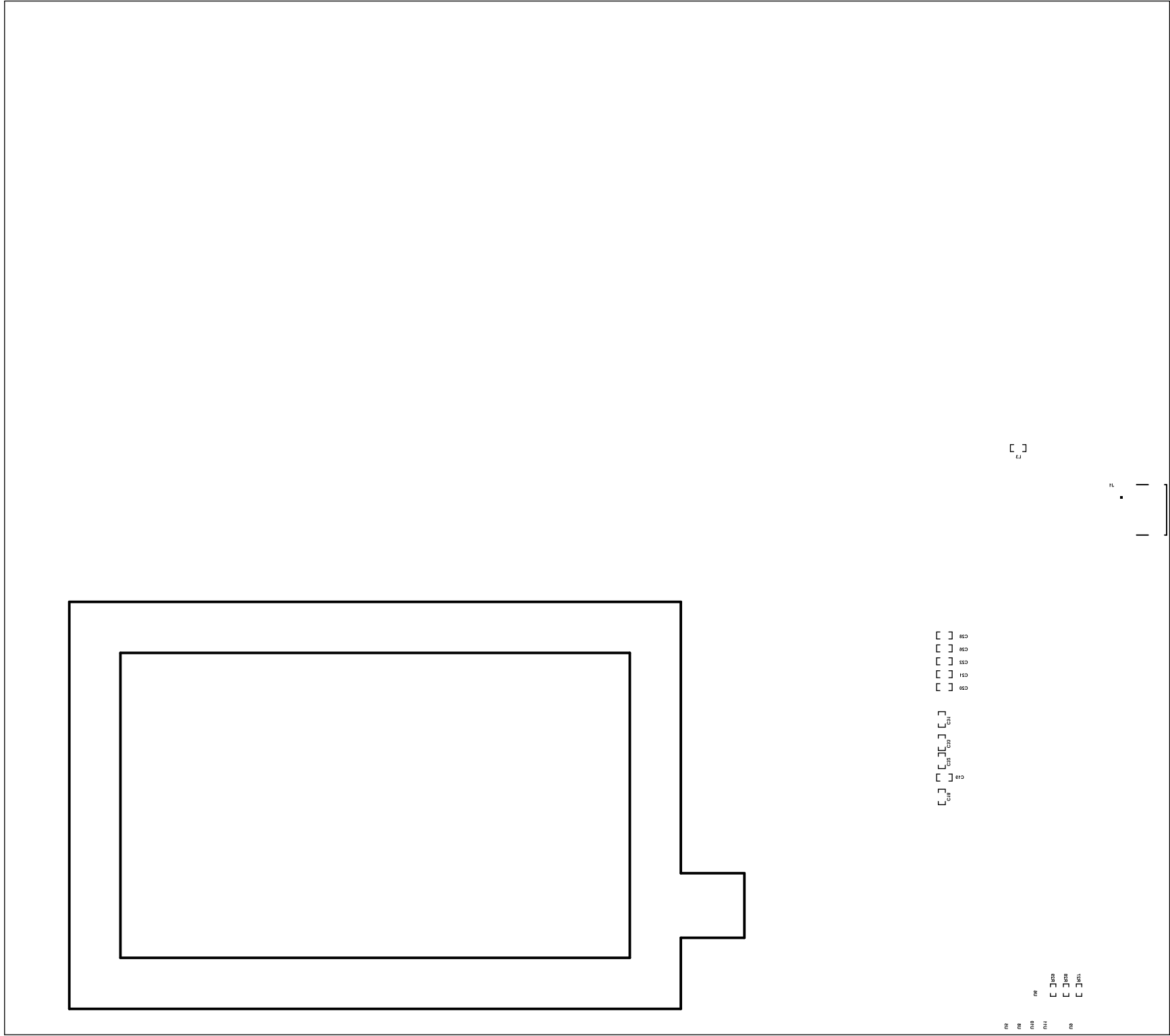
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND			
PLOT NAME = MidLayer2	GENERATED : 10/14/2014 2:57:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/14/2014 2:57:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/14/2014 2:57:38 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/14/2014 2:57:38 PM	TEXAS INSTRUMENTS	

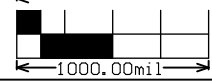




Symbol	Hit Count	Tool Size	Plated	Hole Type
□	12	7.874mil (0.2mm)	PTH	Round
○	320	10mil (0.254mm)	PTH	Round
⊗	26	31.496mil (0.8mm)	PTH	Round
⊗	3	33.465mil (0.85mm)	PTH	Round
*	2	35.433mil (0.9mm)	NPTH	Round
▽	42	40mil (1.016mm)	PTH	Round
⊗	4	57.087mil (1.45mm)	NPTH	Round
◇	9	125.984mil (3.2mm)	PTH	Round
418 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/14/2014 2:57:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/14/2014 2:57:40 PM	TEXAS INSTRUMENTS	

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